

40V P-Channel MOSFET

Product Summary

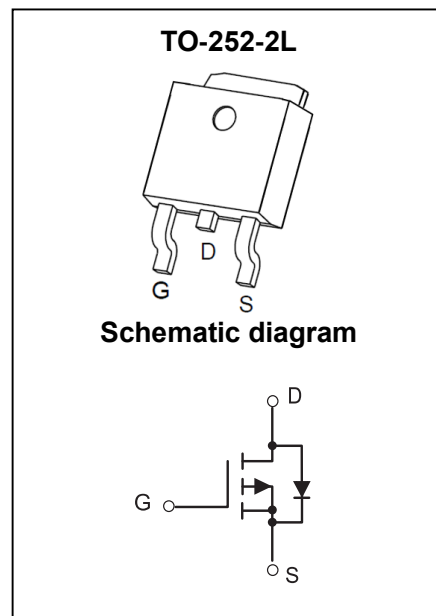
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
-40V	10mΩ@-10V	-50A
	15mΩ@-4.5V	

Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power Switching Application
- DC/DC Converter



Package Marking and Ordering Information

Part Number	Package	Marking	Packing	Reel Size	Tape Width	Qty
M110P04LTF	TO-252-2L	M110P04L	Reel & Tape	330mm	16mm	2500pcs

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	-40	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current ¹	$T_C = 25^\circ\text{C}$	I_D	-50	A
	$T_C = 100^\circ\text{C}$	I_D	-31	A
Pulsed Drain Current ²		I_{DM}	-200	A
Single Pulsed Avalanche Current ³		I_{AS}	-30	A
Single Pulsed Avalanche Energy ³		E_{AS}	225	mJ
Power Dissipation ⁵	$T_C = 25^\circ\text{C}$	P_D	55	W
Thermal Resistance from Junction to Ambient ⁶		$R_{\theta JA}$	50	$^\circ\text{C/W}$
Thermal Resistance from Junction to Case		$R_{\theta JC}$	2.27	$^\circ\text{C/W}$
Junction Temperature		T_J	150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55~ +150	$^\circ\text{C}$

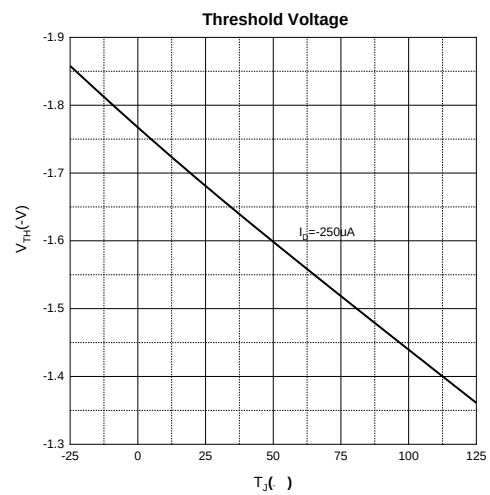
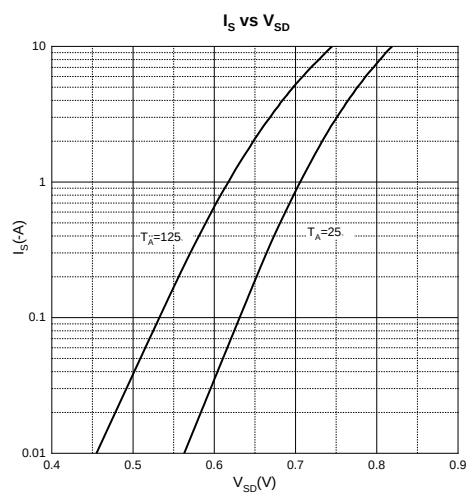
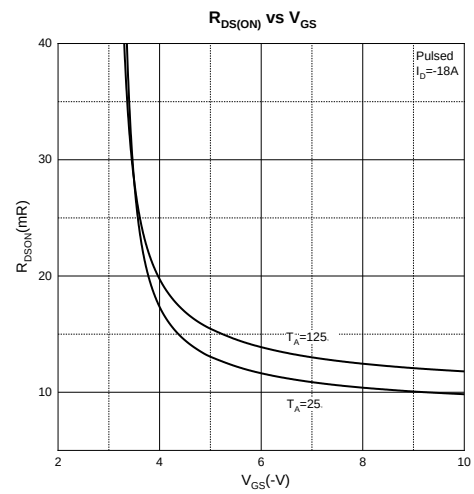
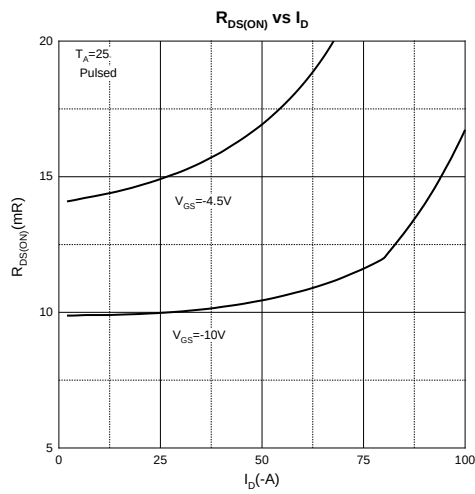
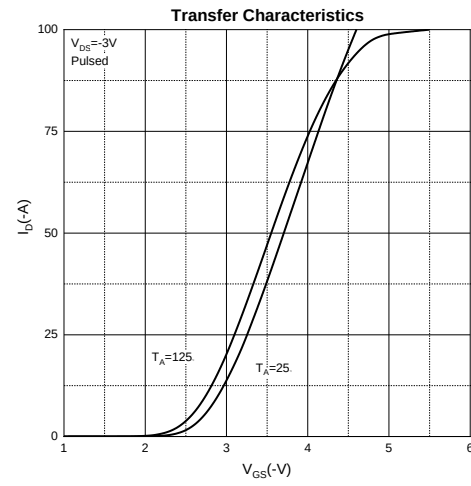
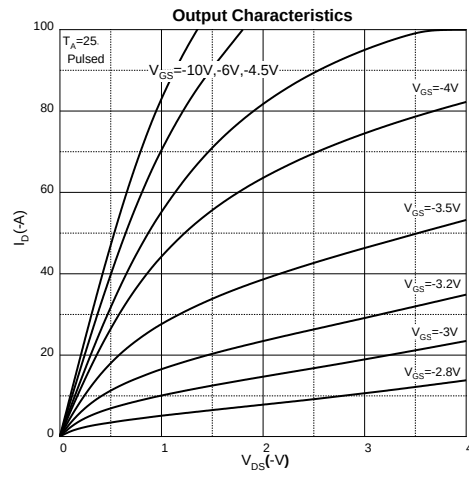
Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-40			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -40V, V _{GS} = 0V			-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
On Characteristics ⁴						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1.0	-1.7	-3.0	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = -10V, I _D = -18A		10	14	mΩ
		V _{GS} = -4.5V, I _D = -12A		15	19	
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = -20V, V _{GS} = 0V, f = 1MHz		2609		pF
Output Capacitance	C _{oss}			261		
Reverse Transfer Capacitance	C _{rss}			231		
Gate Resistance	R _g	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz		8.7		Ω
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} = -20V, V _{GS} = -10V, I _D = -12A		59		nC
Gate-Source Charge	Q _{gs}			8		
Gate-Drain Charge	Q _{gd}			13		
Turn-On Delay Time	t _{d(on)}	V _{DD} = -15V, V _{GS} = -10V, I _D = -18A, R _G = 3Ω		33		ns
Turn-On Rise Time	t _r			28		
Turn-Off Delay Time	t _{d(off)}			85		
Turn-Off Fall Time	t _f			9		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	V _{GS} = 0V, I _S = -10A			1.2	V

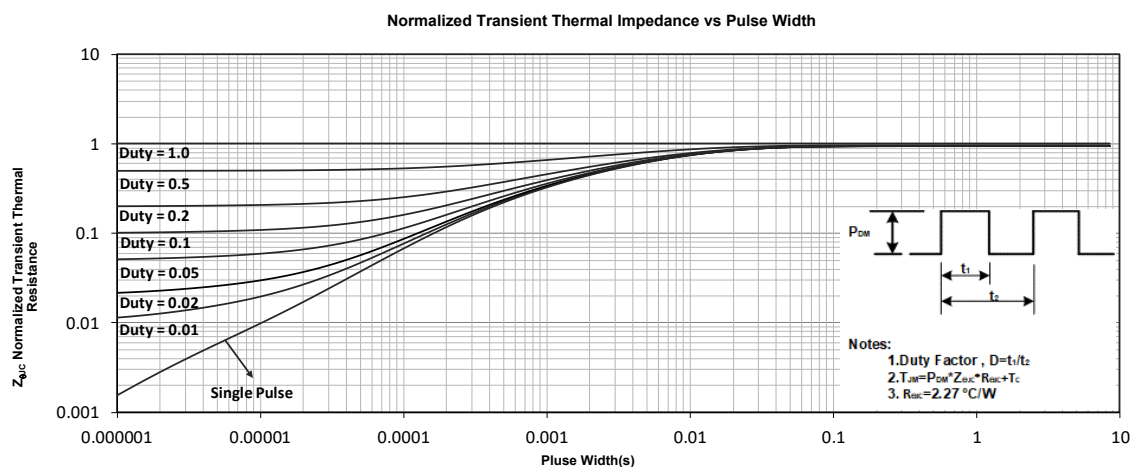
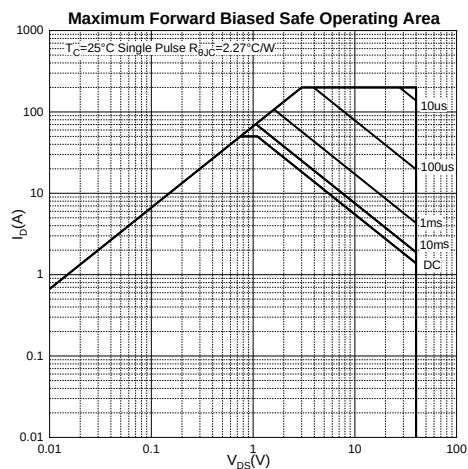
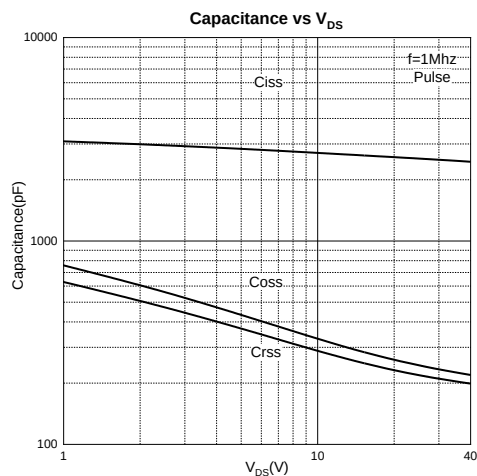
Notes :

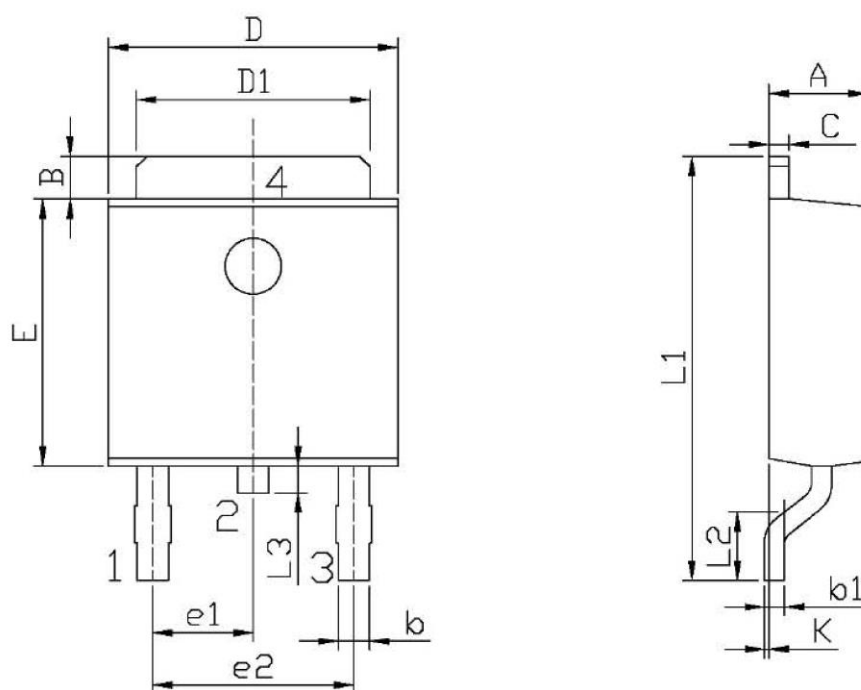
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD} = -20V, V_{GS} = -10V, L = 0.5mH, R_G = 25\Omega$ Starting $T_J = 25^{\circ}\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)} = 150^{\circ}\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^{\circ}\text{C}$.

Typical Characteristics



Typical Characteristics





Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
B	0.950	1.250	0.037	0.049
b	0.500	0.700	0.020	0.028
b1	0.450	0.550	0.018	0.022
C	0.450	0.550	0.018	0.022
D	6.450	6.750	0.254	0.266
D1	5.100	5.500	0.201	0.217
E	5.950	6.250	0.234	0.246
e1	2.240	2.340	0.088	0.092
e2	4.430	4.730	0.174	0.186
L1	9.450	9.950	0.372	0.392
L2	1.250	1.750	0.049	0.069
L3	0.600	0.900	0.024	0.035
K	0.000	0.100	0.000	0.004